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**Adhesives — Test methods for  
isotropic electrically conductive  
adhesives —**

**Part 8:  
Electrochemical migration test  
methods**

*Adhésifs — Méthodes d'essai pour adhésifs à conductivité électrique  
isotrope —*

*Partie 8: Méthodes d'essai de migration électrochimique*



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Published in Switzerland

# Contents

	Page
Foreword .....	iv
<b>1 Scope</b> .....	<b>1</b>
<b>2 Normative references</b> .....	<b>1</b>
<b>3 Terms and definitions</b> .....	<b>1</b>
<b>4 Principle</b> .....	<b>2</b>
<b>5 Apparatus and test circuit board</b> .....	<b>2</b>
5.1 Preparation of test coupon .....	4
5.2 Measurement wiring .....	4
<b>6 Test</b> .....	<b>5</b>
6.1 Test conditions .....	5
6.2 Test procedure .....	5
6.3 Judgment .....	8
<b>7 Test report</b> .....	<b>8</b>
<b>Bibliography</b> .....	<b>9</b>

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## Foreword

ISO (the International Organization for Standardization) is a worldwide federation of national standards bodies (ISO member bodies). The work of preparing International Standards is normally carried out through ISO technical committees. Each member body interested in a subject for which a technical committee has been established has the right to be represented on that committee. International organizations, governmental and non-governmental, in liaison with ISO, also take part in the work. ISO collaborates closely with the International Electrotechnical Commission (IEC) on all matters of electrotechnical standardization.

The procedures used to develop this document and those intended for its further maintenance are described in the ISO/IEC Directives, Part 1. In particular the different approval criteria needed for the different types of ISO documents should be noted. This document was drafted in accordance with the editorial rules of the ISO/IEC Directives, Part 2. [www.iso.org/directives](http://www.iso.org/directives)

Attention is drawn to the possibility that some of the elements of this document may be the subject of patent rights. ISO shall not be held responsible for identifying any or all such patent rights. Details of any patent rights identified during the development of the document will be in the Introduction and/or on the ISO list of patent declarations received. [www.iso.org/patents](http://www.iso.org/patents)

Any trade name used in this document is information given for the convenience of users and does not constitute an endorsement.

The committee responsible for this document is ISO/TC 61, *Plastics*, Subcommittee SC 11, *Products*.

ISO 16525 consists of the following parts, under the general title *Adhesives — Test methods for isotropic electrically conductive adhesives*:

- *Part 1: General test methods*
- *Part 2: Determination of electrical characteristics*
- *Part 3: Determination of heat transfer properties*
- *Part 4: Determination of shear strength and electrical resistance using rigid-to-rigid bonded assemblies*
- *Part 5: Determination of shear fatigue*
- *Part 6: Determination of pendulum-type shear impact*
- *Part 7: Environmental test methods*
- *Part 8: Electrochemical-migration test methods*
- *Part 9: Determination of high-speed signal-transmission characteristics*

# Adhesives — Test methods for isotropic electrically conductive adhesives —

## Part 8: Electrochemical-migration test methods

**SAFETY STATEMENT** — Persons using this part of ISO 16525 should be familiar with normal laboratory practice. This part of ISO 16525 does not purport to address all of the safety problems, if any, associated with its use. It is the responsibility of the user to establish appropriate safety and health practices and to ensure compliance with any regulatory conditions.

**IMPORTANT** — Certain procedures specified in this part of ISO 16525 might involve the use or generation of substances, or the generation of waste, that could constitute a local environmental hazard. Reference should be made to appropriate documentation on safe handling and disposal after use.

### 1 Scope

This part of ISO 16525 specifies test methods for confirming the occurrence of electrochemical migration in electrically isotropic conductive adhesives at high-temperature and humidity. The electrical resistance is also determined.

### 2 Normative references

The following documents, in whole or in part, are normatively referenced in this document and are indispensable for its application. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

ISO 472, *Plastics — Vocabulary*

ISO 291, *Plastics — Standard atmospheres for conditioning and testing*

ISO 9455-17, *Soft soldering fluxes — Test methods — Part 17: Surface insulation resistance comb test and electrochemical migration test of flux residues*

IEC 60068-2-67, *Environmental testing — Part 2: Tests — Test Cy: Damp heat, steady state, accelerated test primarily intended for components*

IEC 61249-2-7, *Materials for printed boards and other interconnecting structures — Part 2-7: Reinforced base materials clad and unclad — Epoxide woven E-glass laminated sheet of defined flammability (vertical burning test), copper-clad*

### 3 Terms and definitions

For the purposes of this document, the terms and definitions given in ISO 472 and ISO 9455-17 and the following apply.

**3.1  
electrochemical migration**

electrochemical failure that occurs when voltage is applied between electrodes using electrically isotropic conductive adhesives where there is moisture and when, through migration and cathodic deposition, the electrodes dissolve, resulting in a short-circuit

Note 1 to entry: It is accelerated by temperature, humidity, and voltage.

**3.2  
comb-pattern electrode**

comb-pattern test circuit formed on a printed circuit board

## 4 Principle

Comb-pattern electrodes that are formed on a printed circuit board using an electrically isotropic conductive adhesive are exposed to high humidity and voltage is applied between them to check the occurrence of electrochemical migration. To evaluate the occurrence of electrochemical migration, leak currents between the electrodes are measured and changes in insulation resistance recorded. The surface between the electrodes is observed using a microscope after the test to see whether or not electrochemical migration is present.

## 5 Apparatus and test circuit board

**5.1 High-resistance meter**, as specified in ISO 9455-17, able to measure high resistance in the range  $10^6 \Omega$ – $10^{12} \Omega$  with high precision. The range of voltage when measuring resistance is 10 V–100 V.

**5.2 DC power supply**, capable of generating DC voltage in the range 10 V–100 V with high precision.

**5.3 Humidity chamber**, capable of maintaining the specified temperature and humidity in an effective space. To maintain temperature and humidity uniformly, forced air circulation may be used.

**5.4 Microscope**, with magnification of from 50x to 250x and with a light that illuminates the specimen at a luminance of around 2 000 lx.

**5.5 Test coupon**, as follows.

a) **Material of substrate**

Glass fabric-based epoxy resin copper-clad laminate, specified as a general-purpose, single-sided substrate, in accordance with IEC 61249-2-7.

b) **Thickness of substrate**

$1,6 \pm 0,2$  mm or the thickness specified in IEC 61249-2-7.

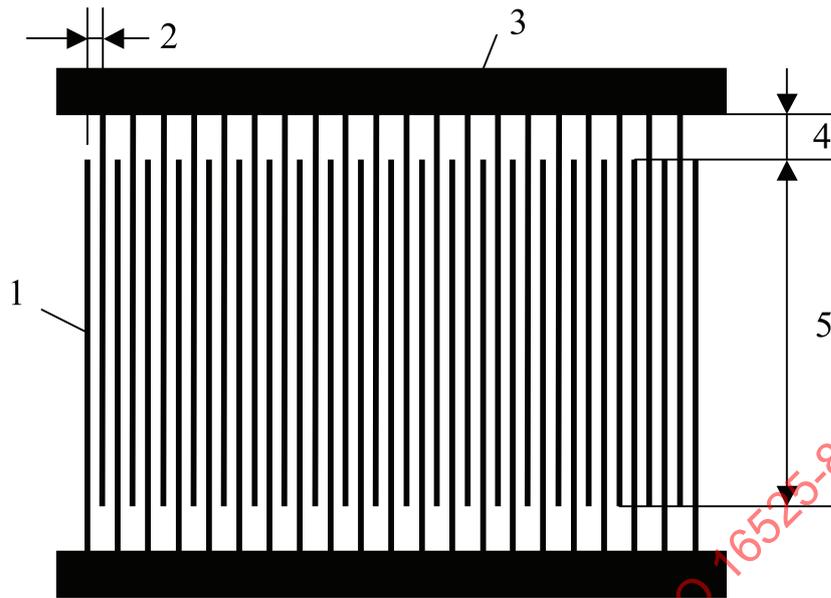
c) **Comb-pattern dimensions**

See [Figure 1](#).

d) **Test coupon layout**

One or the other of the following (see [Figure 2](#)):

- 1) a copper pattern etched into the substrate surface in accordance with the specifications of conductor width;
- 2) a copper pattern etched into the terminal electrodes only.

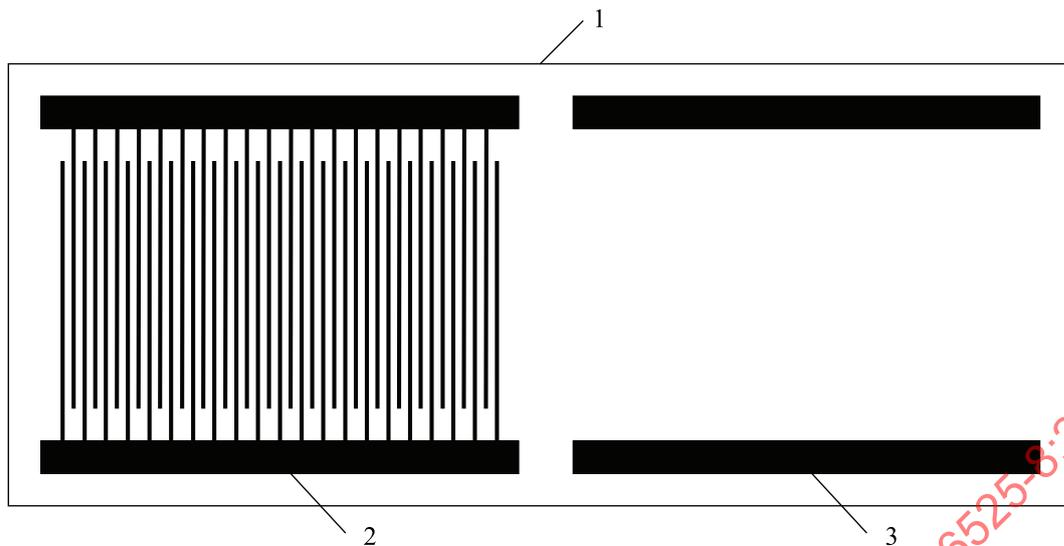


Pattern	A	B
	mm	
CW (1)	0,165	0,318
CG (2)	0,318	
OC (5)	15,75	
d (4)	≥5,0	

**Key**

- |   |                     |   |                                      |
|---|---------------------|---|--------------------------------------|
| 1 | conductor width     | 4 | distance between terminal electrodes |
| 2 | conductor gap       | 5 | overlap of conductor                 |
| 3 | terminal electrodes |   |                                      |

**Figure 1 — Comb pattern of test coupon and stencil mask — Dimensions**



**Key**

- 1 test coupon (glass fabric-based epoxy resin)
- 2 etched copper pattern
- 3 etched only on the terminal electrodes

**Figure 2 — Test coupon layout**

**5.1 Preparation of test coupon**

The test coupon shall be prepared as follows.

- a) Electrically isotropic conductive adhesive

In terms of general behaviour and processes, a paste-type electrically isotropic conductive adhesive containing an organic binder, in which metal particles or flakes disperse, shall be used. Generally, a heat-curing resin is used.

- b) Printing and curing

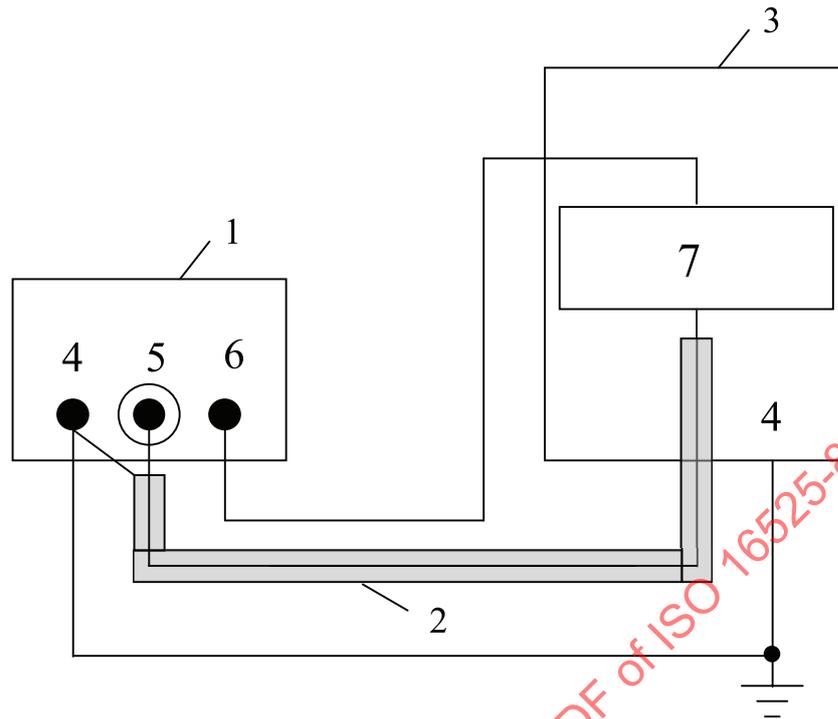
A comb pattern shall be formed by screen-printing the isotropic conductive adhesive onto the substrate. Curing conditions depend on specifications of the electrically isotropic conductive adhesive.

- c) Visual inspection

Visual inspection or microscopic inspection using a microscope shall be performed to check the presence of foreign matter and interelectrode bridge.

**5.2 Measurement wiring**

[Figure 3](#) shows a diagram of measurement wiring. For conductors used to connect the test coupon to the high resistance meter, shielded cables shall be used. When wiring the test bath, a PTFE cable, which is unlikely to emit gas, shall be used. To connect the shielded cables to the electrode on the test circuit board, solder should preferably be used.

**Key**

1	insulation-resistance meter	5	signal input
2	shield-type cable	6	voltage supply
3	humidity chamber	7	test coupon
4	guard (earth)		

**Figure 3 — Diagram of measurement wiring****6 Test****6.1 Test conditions**

The test conditions shall be those given in [Table 1](#), unless otherwise specified in the product specifications, and shall be in accordance with ISO 9455-17 and IEC 60068-2-67.

**Table 1 — Test conditions**

Test temperature °C	Test humidity %	Bias voltage V/DC	Measuring voltage V/DC	Duration h
$85 \pm 2$	$85^{+2}_{-3}$	50	50	1 000

**6.2 Test procedure**

The test procedure is as follows:

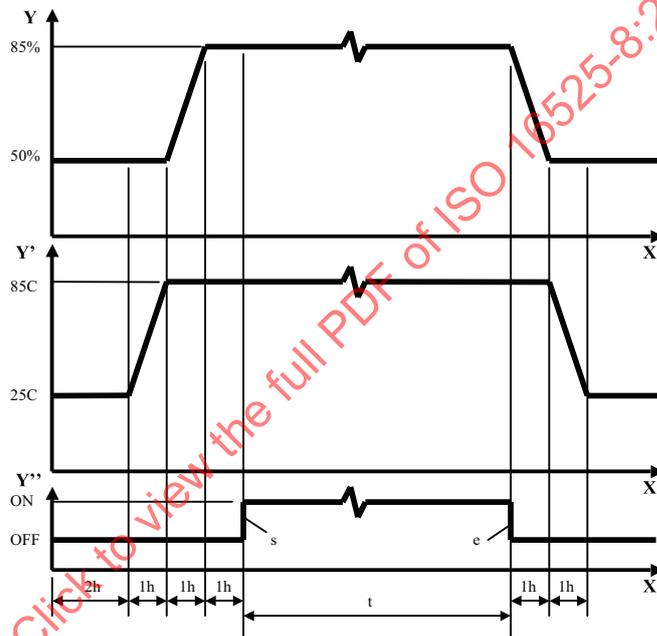
**a) Initial measurement**

Visual inspection or microscopic inspection shall be used to check appearance; record the value of insulation resistance at a standard temperature of  $25 \pm 2$  °C and standard humidity of  $50 \pm 5$  % in accordance with ISO 291.

b) **Testing**

Place a test coupon in the test bath in accordance with [6.1](#) and apply bias voltage after temperature and humidity have reached the specified conditions from normal conditions, as shown in [Figure 4](#).

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**Key**

- X time, h
- Y relative humidity, % RH
- Y' temperature, °C
- Y'' bias voltage, V/DC
- e end of test
- s start of test
- t duration (time)

**Figure 4 — Test profile**